

Semi-Automatic Wire Bonder Ball , Wedge & Bump



The WB-200 series are designed as a multi-purposes semiautomatic wire bond tool for R&D purpose, prototype and small series production.

The WB-200 provides also a full manual Z Step control for prototyping or simple repair, no mechanical set-up required...

Bench Top size with small foot print...

All configurations: Flat Substrates, Deep and Large Packages...

Powerful Video/Focus capability compatible with small bond patterns, and multi-Bond heights application.

Package Walls or Access unrestricted.

This is the new generation of JFP wire bonder, with enhanced functionality, into a robust and reliable mechanical concept.

SYSTEM

- Table Top machine
- Bond Arm Length: 165mm (6.7")
- Deep-Access bond Head
- Motorized Z Bond Head
True vertical motion
Z travel = 40mm, Z accuracy = 1µm
- Motorized X & Y : 50x50mm, X&Y accuracy 2µm
- Mouse Motion Drive
- Ultrasonic power: 0-2 to 10 Watt
Transducer : WBT140 : 62kHz, 185mm Long
Other Frequency on request
- Motorized up-down Clamp
- Automatic motorized wire Spool: 2"
- Electronic Flame-off
- Missing Ball detection

3 BONDING MODES

- SEMI-AUTO with Binocular
- Full MANUAL Z, with Binocular
- AUTO-BOND Cycle with Vertical Camera
Multi-Height Focus

PARAMETERS

- Digital programming
- Bond Force I and II programmable: 5-100 cN
- Time I and II programmable: 0-5000 ms
- Power I and II programmable
- Loop: Reverse+Height+Length
Multi-shape Loop programmable per wire
- Bond: Search Height programmable
Automatic Bond Height detection
- Tail length programmable
- Wire termination: Table Tear / Clamp Tear
- Wedge Deep Access 90° wire feeding
- Multiple wires can be chain
- Wire capability:
Gold wire: 17-50µm
Aluminium wire: 17-50µm
Ribbon wire: 40-200µm width (12-25µm Thick)
- Touch screen interface : 7" Simatic
Storage: 50 programs
Programs saveable, unlimited on USB stick
- Temperature programmable
- Heater Stage HP60-250°C
T° accuracy +/- 1%,
Adjustable Height
Working Height 100mm

OPTIONAL Configuration

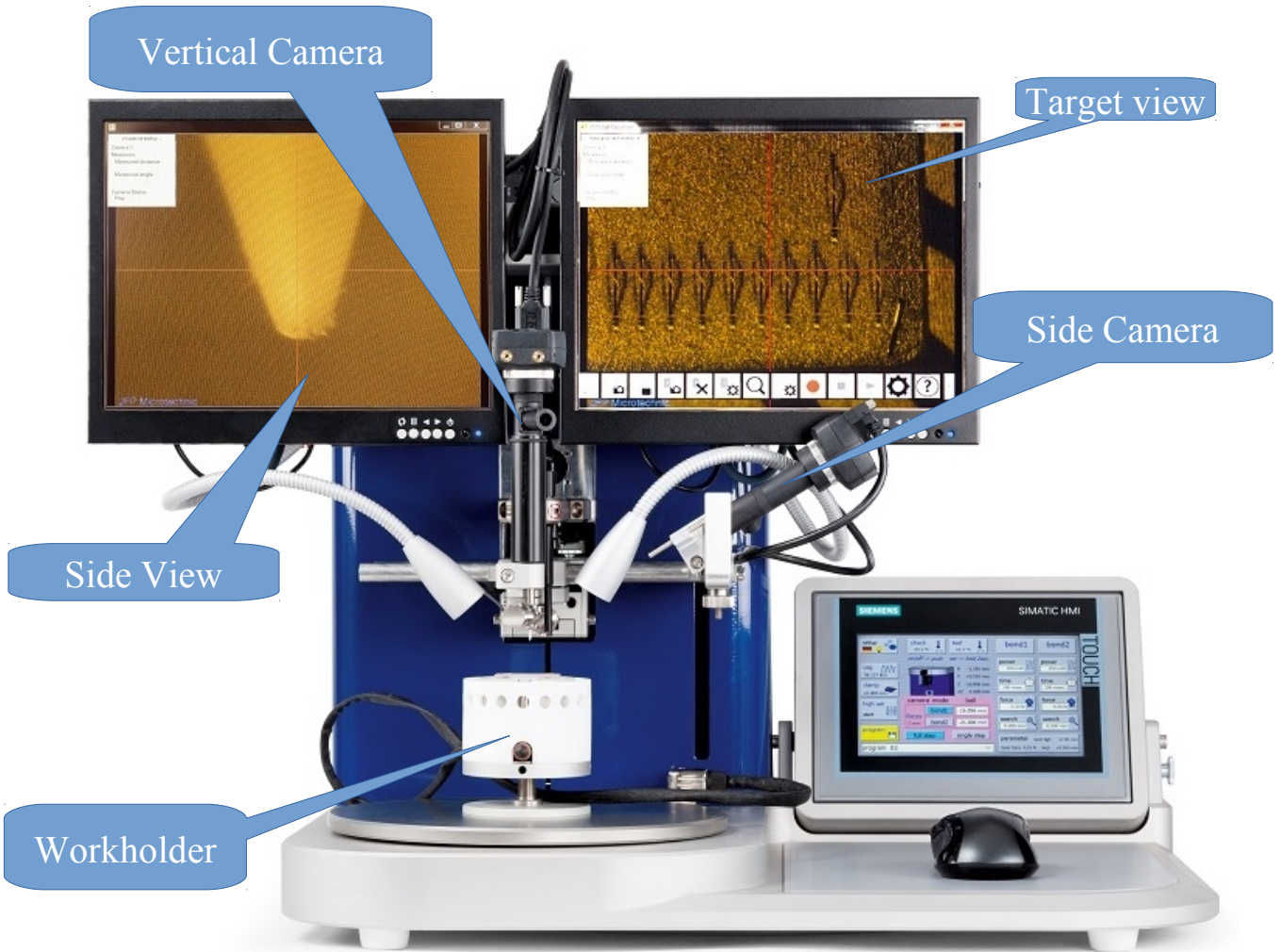
- Vertical Camera, No parallax,
- Field of View, FOV, **Compatible for very Fine Pitch**
- Digital crossHair, square or circular pattern
- Light: Led illumination

JFP WB200-1



The machines which require minimal training to operate

CAMERA MODE



VERTICAL CAMERA

Operator can directly use the vertical vision to precisely center the bonding pads, with no error. A powerful digital zoom, to easily perform fine pitch applications. A fine focusing capability, to view over 20mm height difference between 1st Bond and 2nd Bond .

SIDE CAMERA

This option is very useful to check the wire during Bond and Loop, Loop shape and motion can be recorded during bonding, for further analysis. The high definition video format is compatible with UHD TV/Monitors... Side camera Picture is always at "focus" distance,, no other setup is required...

WB200 BONDING MODES

- Full Manual Z control, with Binocular
- SEMI-AUTO with Binocular
- CAMERA MODE or AUTO-BOND
Binocular not required to operate



SIDE

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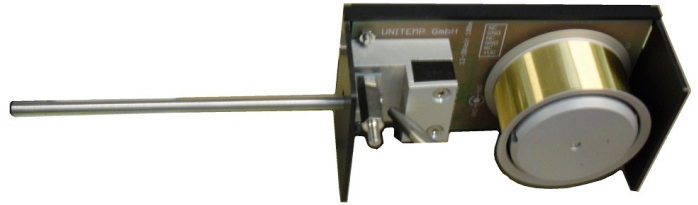
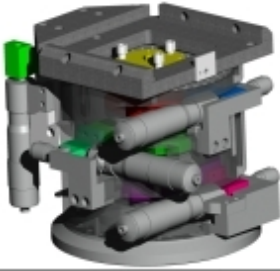
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VARIOUS

AUTOMATIC WIRE DESPOOLER

Extra spare to be used as storage and wire identifier purposes



TAB - Heated Workholder

Chip to lead frame assembly...
Lead width 40µm
Frame holder 50x50mm

OPTIONS

- HP-60 Heated Workholder 60mm diameter
- HP-80 Heated Workholder 80mm diameter
- HP-100 Heated Workholder 100 x100 mm
- HP-150 Heated Workholder 150 x 100 mm
- HP-200 Heated Workholder 200 x 150 mm
- TH-TC Tool Heater with Thermocouple
- More options
- 90° Pivoting work-holder

TECHNICAL DATA

- Ultrasonic system: PLL, 62khz
- Power: 0-2 watt
- Bond Time: 15-5000 msec
- Force: 15- 100 cNm
- Capillary tool: 1,58mm (1/16") diameter
- Z travel, motorized : 20 mm
- Throat depth
- Mouse ratio 6:1
- Fine x -Y motion : 20 mm



HP60



HP-100



HP-200

TECHNICAL REQUIREMENTS

Power	100 / 240V , 50-60Hz
Current:	max. 5A
Dimensions:	580*510*490 mm (23"x21"x19")
Weight:	45 kg.



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